

Asia Pacific System in Package (SiP) Technology Market (2016-2022)

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Abstracts

The Asia Pacific System in Package (SiP) Technology Market is would register a growth of 8.5% CAGR during the forecast period (2016-2022).

Growth in Internet of Things (IoT) and adoption of SiP technology in graphic cards and processors for real world gaming have significantly increased the rate of adoption of SiP in consumer electronics, automotive, telecommunication, and other sectors. Due to the aforementioned factors, the Asia Pacific SiP market is anticipated to witness growth during the forecast period. However, high cost and customization limits would hamper the market growth. The demand for high frequency electronic gadgets would have a positive impact on the market.

The Asia Pacific system in package (SiP) technology market would witness significant growth during the forecast period due to growing demand for portable electronic devices and growing popularity of Internet of Things (IoT). Printed circuit board (PCB) based ICs were mostly used in industrial systems for data transmission. However, other industries such as consumer electronics, energy & power, inverter & UPS, and automotive, have shifted to SiP to efficiently manage data transfer. The Sip technology is an advanced technology and as the levels of awareness increase, the demand for SiP would significantly grow.

The report highlights the adoption of System in Package (SiP) Technology in Asia Pacific. Based on the Type, the Asia Pacific System in Package (SiP) Technology market is segmented into 2-D IC Packaging, 2.5-D IC Packaging and 3-D IC Packaging segments. Based on the Packaging Type, the market is bifurcated into Flat Packages, Pin Grid Arrays, Surface Mount, Small Outline Packages and Other Packaging segments. The Asia Pacific System in Package (SiP) Technology market is further

segmented into Wire Bond, Flip Chip segments based on the Interconnection Technology. Further, the market is segmented into Consumer Electronics, Automotive, Telecommunication, Industrial System, Aerospace & Defense and Other segments based on the various applications. The countries included in the report are China, Japan, India, South Korea, Singapore, Malaysia and Rest of Asia Pacific.

Key Players profiled in the report includes Amkor Technology Inc., Jiangsu Changjiang Electronics Technology Co. Ltd., Chipmos Technologies Inc., Powertech Technology Inc., Ase Group, Renesas Electronics Corporation, Samsung Electronics Co. Ltd. and Toshiba Corporation.

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